

100G QSFP28 PAM4 ER1 BIDI Optical Transceiver

Hot Pluggable Simplex LC, +3.3V, 1271/1331nm, EML+APD, Single mode

Model:3CW-QSFP28-23/32-ER

3CW-QSFP28-23-ER&3CW-QSFP28-32-ER BID QSFP28 LR 100G single fiber optical transceiver module are designed for use in 100 Gigabit Ethernet links over 40km single mode fiber. The module incorporate one channel optical signal and operates on 1271nm and 1331nm wavelength. Compliant with the QSFP28 MSA. Digital diagnostics functions are available via the I2C interface, as specified by the QSFP28 MSA.



Features

- QSFP28 MSA package with simplex LC connector
- Compliant to 100G Lamda MSA 100G-LR1 Optical Specifications ī
- Interoperable with IEEE 802.3cu
- Lane signaling rate 53.125GBd with PAM4 ī
- High speed I/O electrical interface
- Two Wire Serial Interface with Digital Diagnostic Monitoring ī
- Operating case temperature range 0°C to +70°C
- ı Support KP4 FEC inside the module and KP4 FEC shutdown
- Reaches up to 10km on SMF
- Maximum power consumption 4.5W
- 3.3V power supply voltage
- compliant to RoHS2.0
- Class 1 Laser Applications
- 100 Gigabit Ethernet ı
- **Data Center**





Absolute Maximum Ratings

Parameter	Symbol	Conditions	Min.	Max.	Unit
Storage temperature (case)	Tstg	-	-40	+85	${\mathbb C}$
Relative Humidity	RH	Noncondensing	5	85	%
Supply voltage	VCC		0	3.6	V
Low speed signal voltage range			-0.3	4.0	>
Damage threshold	Pin	Average		5.5	dBm
ESD Sensitivity		_		±500V for RF ±2kV for others	V

Recommended Operating Conditions

Parameter	Symbol	Min.	Typical	Max.	Unit
Operating Case Temperature	Tcase	0	-	70	ů
Supply Voltage	VCC	3.135	3.3	3.465	V
Relative Humidity	RH	5	-	85	%
Power Dissipation	PD	-	-	4.5	W
Data Rate (optical)	DRO	-	103.125	106.25	Gbps
Data Rate (Electrical)	DRE	-	26.5625	-	Gbps
Operating Link Distance	LD	-	-	10	Km

Optical Characteristics

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	Note
			Transm	itter			
Data Rate				103.125	106.25	Gbps	
Data rate variation			-100		+100	ppm	



		17											
Lane center			1	264.5		1271	1	277.5	nn	n			
wavelength			1	324.5		1331	1	377.5	nn	n			
Launch power Per lane Optical modulation	Peach POMA		-1 0.	.4 7			4.	.5 .7		3m 3m	1, 3	2	
amplitude per lane													
Launch power in	For												
OMA minus	ER>=4.5d B For		-0).7					dE	3m			
	ER<4.5dB		-0	0.6									
Transmitter and Dispersion eye closure	TDECQ						3.	.4	dE	3m			
Optical Extinction													
Ratio Side mode	ER		3.	5					dE	3			_
Suppression ratio	SMSR		30)					dE	3			
Launch power of OF Transmitter per lane	F							-30		dBm			
Relative Intensity Noise	RIN							-136		dB/Hz	<u>z</u>		
Optical retuloss tolerance								15.6		dB			
Transmitter reflectance								-26		dB	4		
			F	Receiv	⁄er								
Data Rate						103.12	25	106.2	25	Gbps			
Data rate variation				-100				+100		Ppm			
				1324	1.5	133′	1	1377	'.5	nm			



Lane center wavelength			1264.5	1271	1277.5	nm		
Damage threshold	Rdam		5.5			dBm	5	
Average receiver power	Rpow		-9.8		4.5	dBm	6	
Receiver power(OMA) per lane	Rovl				4.7	dBm		
Receiver sensitivity (OMA), (max)	SENeach				-10.1	dBm	@BER2.4e- 4	
Stressed Sensitivity per lane	SRS				-8.1	dBm	8	
Receiver reflectance					-28	dB		
LOSS assert	Optical power alarm		-26		-14	dBm		
LOSS de-assert					-12	dBm		
Conditions of str	Conditions of stressed receiver sensitivity test:							
Stressed eye closure for PAM4 (SECQ),					3.4	dB	8	
SECQ- 10*lgCeq					3.4	dB	8	

Note1. As the total average launch power limit has to be met, not all of the lanes can operate at the maximum average launch power ,each lane.

Note2. Average launch power, each lane(min) is informative and not the principal indicator of signal strength. A transmitter with launch power below this value can not be compliant: however, a value above this does not ensure compliance.

Note3. Even if the TDECQ<1.4dB for an extinction ratio of >=4.5dB or TDECQ<1.3dB for an extinction ratio of <4.5dB, the OMA outer (min) must exceed this value.

Note4. Transmitter reflectance is defined looking into the transmitter.

Note5. The receiver shall be able to tolerate, without damage, continuous exposure to an optical input signal having this average power level.



Note6. Average receiver power, each lane(min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance.

Note7. Measured with conformance test signal at TP3 for the BER specified in $\,\,$ 100G-FR and 100G-LR1

Technical Specifications Rev 2.0》

Note8. These test conditions are for measuring stressed receiver sensitivity. They are not characteristics of the receiver.

Electrical Specifications

Transmitter (Module Input)								
Parameter	Symbol	Min.	Typica I	Max.	Unit			
Input Differential Impedance	Rin	-	100	-	Ohm			
Differential termination mismatch (max)	Dmismatch	-	-	10	%			
Differential Data Input Amplitude	VIN,P-P	-	-	900	mVp p			
LPMode, Reset and ModSelL	VIL	-0.3	-	0.8	V			
	VIH	2.0	-	VCC+0.3	V			
Recei	ver (Module (Output)						
Output Differential Impedance	Rout	-	100	1	Ohm			
Differential termination mismatch (max)	Dmismatch	-	-	10	%			
Differential Data Output Amplitude	VOUT,P-P	-	-	900	mVp p			
ModPrsL and IntL	VOL	0	-	0.4	V			
	VOH	VCC-0.5	-	VCC+0.3	V			



Pin layout GND GND 38 TX1n TX1p 2 37 TX2n 36 TX2p GND GND 35 4 Module Card Edge TX3n TX4n 5 34 33 ТХ3р TX4p 6 GND GND 32 31 LPMode ModselL 8 Vcc1 ResetL 30 9 29 VccTx VccRx 10 SCL 28 IntL 11 ModPrsL SDA 27 12 GND GND 26 13 RX4p RX3p 25 14 24 Rx4n Rx3n 15 GND GND 23 16 22 RX2p RX1p 17 RX2n RX1n 21 18 GND GND 19 **Bottom Side** Top Side Viewed From Top Viewed From Bottom

Figure 1 Top Side and Bottom Side of QSFP28

Pin Definitions

Pin no.	Logic	Symbol	Description	Note
1		GND	Ground	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	
4		GND	Ground	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	
7		GND	Ground	1
8	LVTLL-I	ModSelL	Module Select	3
9	LVTLL-I	ResetL	Module Reset	4
10		VccRx	+3.3V Power Supply Receiver	2
11	LVCMOS-I/O	SCL	2-Wire Serial Interface Clock	3
12	LVCMOS-I/O	SDA	2-Wire Serial Interface Data	3
13		GND	Ground	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	



15	CML-O	Rx3n	Receiver Inverted Data Output	
16		GND	Ground	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	
18	CML-O	Rx1n	Receiver Inverted Data Output	
19		GND	Ground	1
20		GND	Ground	1
21	CML-O	Rx2n	Receiver Inverted Data Output	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	
23		GND	Ground	1
24	CML-O	Rx4n	Receiver Inverted Data Output	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	
26		GND	Ground	1
27	LVTTL-O	ModPrsL	Module Present	
28	LVTTL-O	IntL/RX_LOS	Interrupt/Rx LOS	5
29		VccTx	+3.3 V Power Supply transmitter	2
30		Vcc1	+3.3 V Power Supply	2
31	LVTTL-I	LPMode/Tx_DIS	Low Power mode/Tx Disable	5
32		GND	Ground	1
33	CML-I	Тх3р	Transmitter Non-Inverted Data Input	
34	CML-I	Tx3n	Transmitter Inverted Data Input	
35		GND	Ground	1
36	CML-I	Тх1р	Transmitter Non-Inverted Data Input	
37	CML-I	Tx1n	Transmitter Inverted Data Input	
38		GND	Ground	1
	1	I.	<u>I</u>	l

Note1.GND is the symbol for signal and supply (power) common for QSFP28 modules. All are common within the QSFP28 module and all module voltages are referenced to this potential. unless otherwise noted. Connect these directly to the host board signal common ground plane. Note2. Vcc Rx, Vcc1 and Vcc Tx are the receiver and transmitter power suppliers and shall be applied concurrently. Vcc Rx, Vcc1 and Vcc



Tx may be internally connected within the QSFP28 transceiver module in any combination. The connector pins are each rated for a maximum current of 1000mA.

Note3. Timing for SCL, SDA and ModSelL shall comply with the common management interface document SFF-8636 and SFF-8679.

Note4. The QSFP28 module must support hardware reset operation.

Note5.Two Multi-Purpose PIN for supporting Tx_DIS and Rx_LOS function in the 100G QSFP28 module. The IIC interface must function normally when the QSFP28 module is in the LP mode.

Host Board Power Supply Filtering

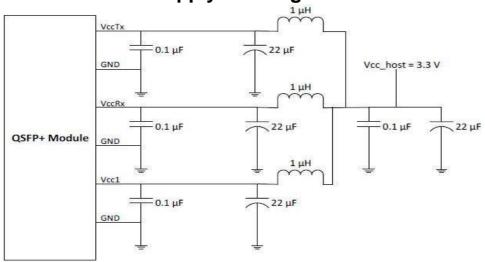


Figure 2 Recommended host board power supply filtering



Mechanical Specifications

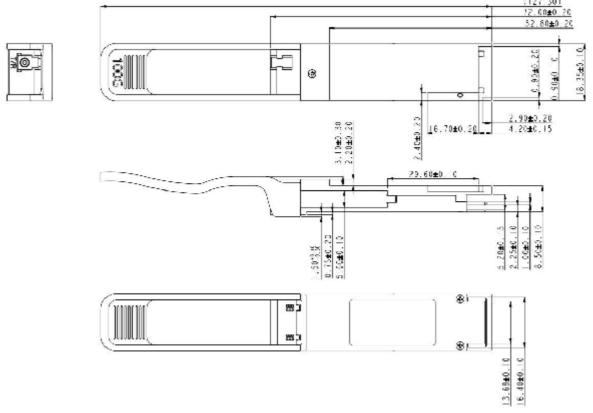


Figure 3 100G ER1 BIDI QSFP28 Mechanical Dimensions

ESD and Reliability

The module meet ESD requirements given in EN61000-4-2, criterion B test specification when installed in a properly grounded cage and chassis. The units are subjected to 15kV air discharges during operation and 8kV direct contact discharges to the case. The module high speed signal contacts shall withstand 500 V electrostatic discharge based on Human Body Model per JEDEC JESD22-A114-B。

The module reliability test and ESD test comply with MIL-STD-883H and Telcordia GR-468-CORE (2004).



Important Notice

Performance figures, data and any illustrative material provided in this data sheet are typical and must be specifically confirmed in writing by 3C-LINK before they become applicable to any particular order or contract. In accordance with the 3C-LINK policy of continuous improvement specifications may change without notice.

The publication of information in this data sheet does not imply freedom from patent or other protective rights of 3C-LINK or others. Further details are available from any 3C-LINK sales representative.











Specifications are subject to change without notice. It is a registered trademark of 3C-LINK Technology Co., Ltd. Other brands and product names are trademarks or registered trademarks of their respective holders. No part of the specifications can reproduced in any form or by any means or used to make any derivative such as translation, transformation, or adaptation without permission from 3C-LINK Technology Co., Ltd.